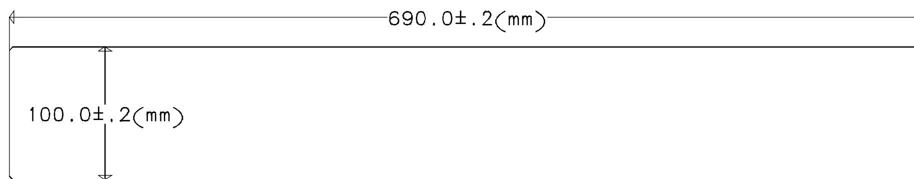
B2319 V3.1 Specification Drawing



B2319 V3.1 PCB Specifications

(1) Board Layers: 8
(2) Layer stack order:
Layer1 (Film1): Top component layer (Signal_1)
Layer2 (Film2): Power plane (VCC2)
Layer3 (Film3): Power plane (VCC), (2oz copper)
Layer4 (Film4): Power plane (GROUND), (2oz copper)
Layer5 (Film5): Inner signal layer (Signal_3)
Layer6 (Film6): Inner signal layer (Signal_4)
Layer7 (Film7): Power plane (VEE)
Layer8 (Film8): Bottom component layer (Signal_2)

(3) Apply solder mask over bare copper on both side:
Film9: Top solder mask (solder_mask_1)
Film10: Bottom solder mask (solder_mask_2)

(4) Apply silkscreen on both side:
Film11: Top silkscreen (Silkscreen_1)
Film12: Bottom silkscreen (Silkscreen_2)

(5) Material: FR4 with Tg> 170C
(6) Board thickness: 0.062'' +/- 0.010''
(7) All layers are equal thickness.
(8) Layer2 (VCC) and Layer3 (GROUND) use 2oz copper before plating, other layers use 1oz copper before plating.
(9) All dimensions are in inches unless otherwise noted.

(10) PCB fabrication meets IPC-6012: Class 2
(11) Bow and Twist: Not exceed 0.75%, Test methods meet IPC-TM-650, L=100mm

(12) Contact person:
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BOARD's DRILL SCHEDULE (Inch)

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
○	.015	475	YES	---
⊞	.02	15	YES	---
⦶	.035	520	YES	---
⊟	.046	60	YES	---
⊖	.059	6	YES	---
◫	.13	6	YES	---
⊕	.14	10	YES	---

SCHM# B2318 V3.1
SPEC# B2319 V3.1
ASSM# B2320 V3.1

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
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SHEET 1 OF 1
DATE 02-23-00
DRAWN TANG

B- 2319
REV 3.1